

Daisuke Yamane

List of Publications by Year in descending order

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71
papers

505
citations

840776

11
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794594

19
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71
all docs

71
docs citations

71
times ranked

318
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 1 | Design of sub-1g microelectromechanical systems accelerometers. Applied Physics Letters, 2014, 104, . | 3.3 | 64 |
| 2 | Pulse electroplating of ultra-fine grained Au films with high compressive strength. Electrochemistry Communications, 2016, 67, 51-54. | 4.7 | 33 |
| 3 | Integrated CMOS-MEMS Technology and Its Applications. ECS Transactions, 2014, 61, 21-39. | 0.5 | 26 |
| 4 | Novel Sensor Structure and Its Evaluation for Integrated Complementary Metal Oxide Semiconductor Microelectromechanical Systems Accelerometer. Japanese Journal of Applied Physics, 2013, 52, 06GL04. | 1.5 | 23 |
| 5 | A Ku-band Dual-SPDT RF-MEMS Switch by Double-Side SOI Bulk Micromachining. Journal of Microelectromechanical Systems, 2011, 20, 1211-1221. | 2.5 | 18 |
| 6 | A dual-axis MEMS capacitive inertial sensor with high-density proof mass. Microsystem Technologies, 2016, 22, 459-464. | 2.0 | 18 |
| 7 | Five-fold sensitivity enhancement in a capacitive tactile sensor by reducing material and structural rigidity. Sensors and Actuators A: Physical, 2019, 293, 167-177. | 4.1 | 18 |
| 8 | Micro-bending testing of electrodeposited gold for applications as movable components in MEMS devices. Microelectronic Engineering, 2017, 180, 15-19. | 2.4 | 17 |
| 9 | Au-Cu Alloys Prepared by Pulse Electrodeposition toward Applications as Movable Micro-Components in Electronic Devices. Journal of the Electrochemical Society, 2018, 165, D58-D63. | 2.9 | 14 |
| 10 | MEMS post-processed self-assembled electret for vibratory energy harvesters. Applied Physics Letters, 2021, 119, . | 3.3 | 13 |
| 11 | Electrical Impedance Monitoring of Photothermal Porated Mammalian Cells. Journal of the Association for Laboratory Automation, 2014, 19, 50-59. | 2.8 | 12 |
| 12 | Structure stability of high aspect ratio Ti/Au two-layer cantilevers for applications in MEMS accelerometers. Microelectronic Engineering, 2016, 159, 90-93. | 2.4 | 12 |
| 13 | An arrayed accelerometer device of a wide range of detection for integrated CMOS-MEMS technology. Japanese Journal of Applied Physics, 2014, 53, 027202. | 1.5 | 11 |
| 14 | Enhancement of mechanical strength in Au films electroplated with supercritical carbon dioxide. Electrochemistry Communications, 2016, 72, 126-130. | 4.7 | 11 |
| 15 | Tensile tests of micro-specimens composed of electroplated gold. Microelectronic Engineering, 2017, 174, 6-10. | 2.4 | 11 |
| 16 | (Invited) CMOS-MEMS Based Microgravity Sensor and Its Application. ECS Transactions, 2020, 97, 91-108. | 0.5 | 11 |
| 17 | Promoted bending strength in micro-cantilevers composed of nanograined gold toward MEMS applications. Microelectronic Engineering, 2018, 196, 20-24. | 2.4 | 10 |
| 18 | Development and Characterization of Vertically Stacked Tactile Sensor With Hollow Structure. IEEE Sensors Journal, 2021, 21, 5809-5818. | 4.7 | 10 |

| # | ARTICLE | IF | CITATIONS |
|----|---|-----|-----------|
| 19 | A 0.1 G-to-20 G integrated MEMS inertial sensor. Japanese Journal of Applied Physics, 2015, 54, 087202. | 1.5 | 9 |
| 20 | High-Strength Electroplated Au-Cu Alloys as Micro-Components in MEMS Devices. Journal of the Electrochemical Society, 2017, 164, D244-D247. | 2.9 | 9 |
| 21 | Development of Multi-User Multi-Chip SOI CMOS-MEMS Processes. , 2009, , . | | 8 |
| 22 | Sample size effect on micro-mechanical properties of gold electroplated with dense carbon dioxide. Surface and Coatings Technology, 2018, 350, 1065-1070. | 4.8 | 8 |
| 23 | Electrodeposition of Ni-Co Alloys and Their Mechanical Properties by Micro-Vickers Hardness Test. Electrochem, 2021, 2, 1-9. | 3.3 | 8 |
| 24 | A capacitive CMOS-MEMS sensor designed by multi-physics simulation for integrated CMOS-MEMS technology. Japanese Journal of Applied Physics, 2014, 53, 04EE15. | 1.5 | 7 |
| 25 | A MEMS Accelerometer for Sub-mG Sensing. Sensors and Materials, 2019, 31, 2883. | 0.5 | 7 |
| 26 | Development of a Dual-SPDT RF-MEMS switch for Ku-band. , 2010, , . | | 6 |
| 27 | Brittle Fracture of Electrodeposited Gold Observed by Micro-Compression. Materials Transactions, 2016, 57, 1257-1260. | 1.2 | 6 |
| 28 | Nanoscale Hierarchical Structure of Twins in Nanograins Embedded with Twins and the Strengthening Effect. Metals, 2019, 9, 987. | 2.3 | 6 |
| 29 | An SOI bulk-micromachined dual SPDT RF-MEMS switch by layer-wise separation design of waveguide and switching mechanism. IEICE Electronics Express, 2010, 7, 80-85. | 0.8 | 5 |
| 30 | An 8 channel, 20 V output CMOS switching driver with 3.3 V power supply using triple-well biasing techniques for integrated MEMS device control. Japanese Journal of Applied Physics, 2014, 53, 04EE13. | 1.5 | 5 |
| 31 | A sub-1G CMOS-MEMS accelerometer. , 2015, , . | | 5 |
| 32 | A study on young's modulus of electroplated gold cantilevers for MEMS devices. , 2017, , . | | 5 |
| 33 | Enhancement in structure stability of gold micro-cantilever by constrained fixed-end in MEMS devices. Microelectronic Engineering, 2018, 187-188, 105-109. | 2.4 | 5 |
| 34 | <i>(Invited)</i> MEMS Accelerometer Fabricated by Gold Multi-Layer Metal Technology. ECS Transactions, 2019, 92, 169-184. | 0.5 | 5 |
| 35 | Sample geometry effect on mechanical property of gold micro-cantilevers by micro-bending test. MRS Communications, 2020, 10, 434-438. | 1.8 | 5 |
| 36 | Deformation behavior of electroplated gold composed of nano-columnar grains embedded in micro-columnar textures. Materials Letters, 2017, 202, 82-85. | 2.6 | 4 |

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|----|--|-----|-----------|
| 37 | A Phase Shifter by LTCC Substrate with an RF-MEMS Switch. , 2008, , . | | 3 |
| 38 | A dual-axis MEMS inertial sensor using multi-layered high-density metal for an arrayed CMOS-MEMS accelerometer. , 2014, , . | | 3 |
| 39 | A design of spring constant arranged for MEMS accelerometer by multi-layer metal technology. , 2016, , . | | 3 |
| 40 | A damping constant model for proof-mass structure design of MEMS inertial sensor by multi-layer metal technology. , 2016, , . | | 3 |
| 41 | Evaluation and modeling of adhesion layer in shock-protection structure for MEMS accelerometer. Microelectronics Reliability, 2016, 66, 78-84. | 1.7 | 3 |
| 42 | (Invited) A 1-mG MEMS Sensor. ECS Transactions, 2016, 72, 7-14. | 0.5 | 3 |
| 43 | Long-term structure stability of Ti/Au layered micro-cantilever evaluated by vibration test. Microelectronic Engineering, 2019, 207, 33-36. | 2.4 | 3 |
| 44 | Cu-alloying effect on structure stability of electrodeposited gold-based micro-cantilever evaluated by long-term vibration test. Microelectronic Engineering, 2019, 215, 111001. | 2.4 | 3 |
| 45 | Strengthening of micro-cantilever by Au/Ti bi-layered structure evaluated by micro-bending test toward MEMS devices. Microelectronic Engineering, 2019, 213, 13-17. | 2.4 | 3 |
| 46 | High-Sensitivity Inertial Sensor Module to Measure Hidden Micro Muscular Sounds. , 2019, , . | | 3 |
| 47 | An Evaluation Method of Brownian Noise in Highly Sensitive Capacitive Sensors. IEEJ Transactions on Sensors and Micromachines, 2015, 135, 142-143. | 0.1 | 3 |
| 48 | Electrodeposition and Micro-Mechanical Property Characterization of Nickel–Cobalt Alloys toward Design of MEMS Components. Electrochem, 2022, 3, 198-210. | 3.3 | 3 |
| 49 | A dual-SPDT RF-MEMS switch on a small-sized LTCC phase shifter for Ku-band operation. , 2009, , . | | 2 |
| 50 | Sub-1G MEMS accelerometer. , 2013, , . | | 2 |
| 51 | (Invited) A Sub-1G MEMS Sensor. ECS Transactions, 2015, 66, 131-138. | 0.5 | 2 |
| 52 | Long-term vibration characteristics of MEMS inertial sensors by multi-layer metal technology. , 2017, , . | | 2 |
| 53 | High Strength Electrodeposited Au-Cu Alloys Evaluated by Bending Test toward Movable Micro-Components. ECS Journal of Solid State Science and Technology, 2019, 8, P412-P415. | 1.8 | 2 |
| 54 | Alloy Electroplating and Young’s Modulus Characterization of AuCu Alloy Microcantilevers. Journal of the Electrochemical Society, 2020, 167, 082503. | 2.9 | 2 |

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|----|--|-----|-----------|
| 55 | Effective Young's Modulus of Complex Three Dimensional Multilayered Ti/Au Micro-Cantilevers Fabricated by Electrodeposition and the Temperature Dependency. <i>Electrochem</i> , 2021, 2, 216-223. | 3.3 | 2 |
| 56 | Effect of current density on micro-mechanical property of electrodeposited gold film evaluated by micro-compression. <i>Surface and Coatings Technology</i> , 2022, 436, 128315. | 4.8 | 2 |
| 57 | A 12GHz bulk-micromachined RF-MEMS phase shifter by SOI layer-separation design. <i>IEICE Electronics Express</i> , 2010, 7, 1785-1789. | 0.8 | 1 |
| 58 | Monolithic integration of passive RF components by MEMS. , 2011, , . | | 1 |
| 59 | Development of high sensitivity CMOS-MEMS inertia sensor and its application to early-stage diagnosis of Parkinson's disease. , 2016, , . | | 1 |
| 60 | A 0.18- μ m CMOS time-domain capacitive-sensor interface for sub-1mG MEMS accelerometers. <i>IEICE Electronics Express</i> , 2018, 15, 20171227-20171227. | 0.8 | 1 |
| 61 | Electrodeposition of Gold Alloys and the Mechanical Properties. , 2019, , . | | 1 |
| 62 | Multi-Physics Simulation Platform and Multi-Layer Metal Technology for CMOS-MEMS Accelerometer with Gold Proof Mass. , 0, , . | | 1 |
| 63 | Fabrication of Au-Cu Alloy/Ti Layered Micro-Cantilevers and the Long-Term Structure Stability. , 2019, , . | | 1 |
| 64 | Co-Electrodeposition of Au-TiO ₂ Nanocomposite and the Micro-Mechanical Properties. <i>Electrochem</i> , 2020, 1, 388-393. | 3.3 | 1 |
| 65 | Real-time monitoring of photothermal porated mammalian cells by electric impedance sensors. , 2012, , . | | 0 |
| 66 | A 1mG-to-20G integrated MEMS inertial sensor. , 2014, , . | | 0 |
| 67 | Development of high sensitivity CMOS-MEMS inertia sensor and its application to early-stage diagnosis of Parkinson's disease. , 2016, , . | | 0 |
| 68 | Extensive Sensitivity Enhancement in Stacked Capacitive Tactile Sensors. , 2019, , . | | 0 |
| 69 | Energy Harvesting from Non-Stationary Vibrations Using a Low-Threshold Voltage-Boost Rectifier Circuit. <i>IEEJ Transactions on Sensors and Micromachines</i> , 2021, 141, 228-232. | 0.1 | 0 |
| 70 | A Fabrication Process of MEMS Coplanar Waveguides Using a Thick Plated Gold Layer as DRIE Mask. <i>IEEJ Transactions on Sensors and Micromachines</i> , 2011, 131, 130-131. | 0.1 | 0 |
| 71 | Microgravity Generation Using Tilting Board for Resolution Evaluation of MEMS Accelerometer. <i>Sensors and Materials</i> , 2018, 30, 2919. | 0.5 | 0 |